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elower 10,2003

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

: Matthias Stecher et al. Applicant

: 10/073,847 Applic. No.

: February 11, 2002 Filed

Title : SOI Component

Examiner : Mark V. Prenty

Group Art Unit: 2822

TECHNOLOGY CENTER 2800

AMENDMENT

Hon. Commissioner of Patents and Trademarks, Washington, D. C. 20231

Sir:

Responsive to the Office action dated November 8, 2002 kindly amend the above-identified application as follows:

In the Claims:

Claim 1 (amended). A semiconductor component, comprising:

a semiconductor substrate;